

HVB350BYP

Silicon Epitaxial Planar Variable Capacitance Diode for VCO

REJ03G0487-0100 (Previous: ADE-208-1420) Rev.1.00 Jan 11, 2005

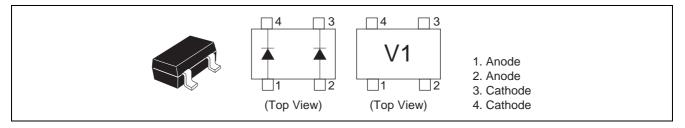
Features

- High capacitance ratio. (n = 2.8 min)
- Low series resistance. (rs = 0.5 max)
- Good C-V linearity.
- CMPAK-4 Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HVB350BYP	V1	CMPAK-4

Pin Arrangement





Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

ltem	Symbol	Value	Unit
Reverse voltage	V _R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

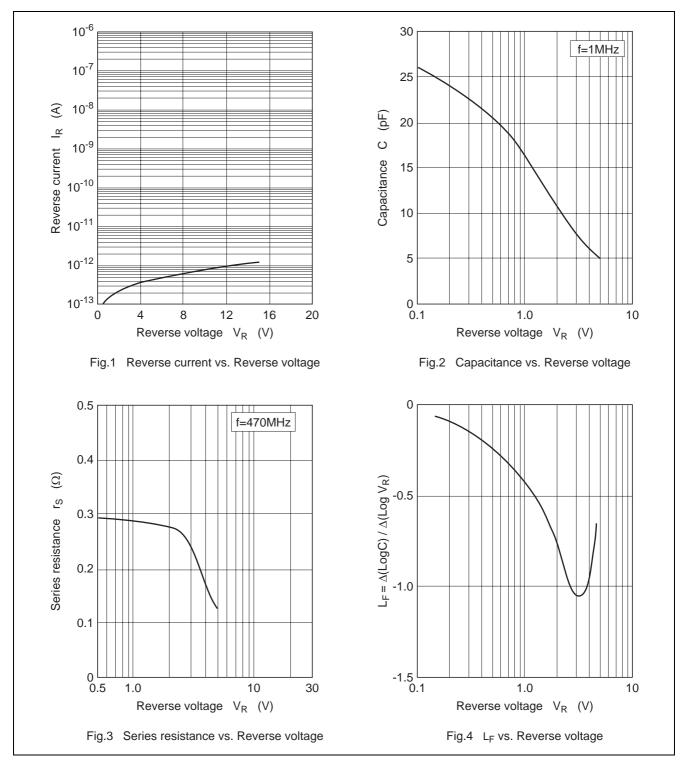
Electrical Characteristics

 $(Ta = 25^{\circ}C)$ Item Symbol Min Max Unit **Test Condition** Тур 10 V_R = 15 V Reverse current I_{R1} nA — — 100 V_R = 15 V, Ta = 60°C I_{R2} — рF Capacitance C_1 15.5 _ 17.0 V_R = 1 V, f = 1 MHz $V_R = 4 V, f = 1 MHz$ C_4 5.0 6.0 ____ Capacitance ratio 2.8 C₁ / C₄ n ____ ____ 0.5 V_R = 1 V, f = 470 MHz Series resistance rs — ____ Ω

Note: 1. Per one device.

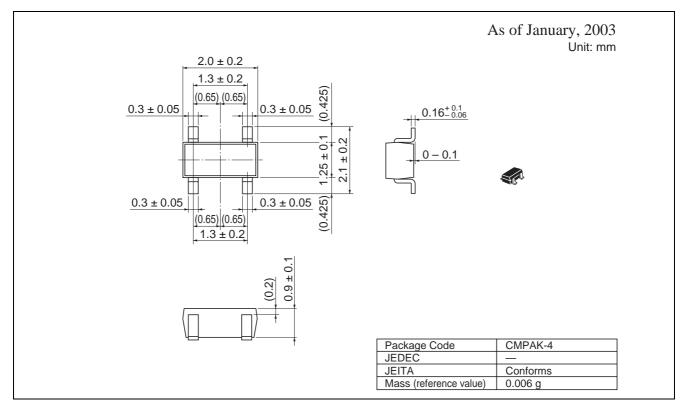


Main Characteristic





Package Dimensions





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